

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ISC046N04NM5	**Issued**	24. February 2022
MA#	MA005708623		
Package	PG-TDSON-8-37	**Weight***	113.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.359	0.31	0.31	3146	3146
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		428	
	non noble metal	copper	7440-50-8	48.769	42.80	42.85	427847	428404
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	399	399
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		745	
	plastics	epoxy resin	-	6.713	5.89		58894	
	inorganic material	silicondioxide	60676-86-0	35.690	31.31	37.27	313108	372747
leadfinish	non noble metal	tin	7440-31-5	1.392	1.22	1.22	12208	12208
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1700	1700
solder	non noble metal	tin	7440-31-5	0.011	0.01		96	
	noble metal	silver	7440-22-4	0.014	0.01		120	
	non noble metal	lead	7439-92-1	0.523	0.46	0.48	4592	4808
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	non noble metal	copper	7440-50-8	17.131	15.03	15.05	150292	150487
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.61	2.61	26067	26101
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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